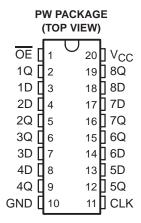
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- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -40°C to 105°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree†
- Typical V_{OI P} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) $>2.3 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- **Supports Mixed-Mode Voltage Operation on All Ports**
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Ioff Supports Partial-Power-Down Mode Operation
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



description/ordering information

The SN74LV374A is an octal edge-triggered D-type flip-flop designed for 2-V to 5.5-V V_{CC} operation.

This device features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

TA	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP - PW	Tape and reel	SN74LV374ATPWREP	LV374AEP

[‡]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

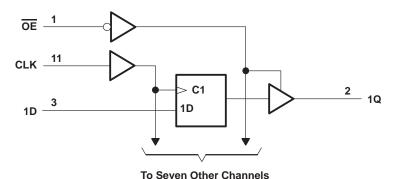
To ensure the high-impedance state during power up or power down, $\overline{\sf OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
OE	CLK	D	Q
L	↑	Н	Н
L	\uparrow	L	L
L	L	Χ	Q_0
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or	
power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3)	83°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2	5.5	V	
		V _{CC} = 2 V	1.5			
.,	High level input valte me	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V	
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V _{CC} ×0.7		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7			
		V _{CC} = 2 V		0.5		
V/	Low level input veltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V	
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$VCC \times 0.3$		
٧ _I	Input voltage		0	5.5	V	
\/ -	Output valle ve	High or low state	0	VCC	٧	
۷O	Output voltage	3-state	0	5.5	V	
		V _{CC} = 2 V		-50	μΑ	
	USah, Lovel and and an annual	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		
ЮН	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-8	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-16		
		V _{CC} = 2 V		50	μΑ	
1	Laur laural autaut aussaut	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		
lOL	Low-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		8	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		16		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		
TA	Operating free-air temperature		-40	105	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			
	I _{OH} = -2 mA	2.3 V	2			.,
VOН	I _{OH} = -8 mA	3 V	2.48			V
	I _{OH} = -16 mA	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
.,	I _{OL} = 2 mA	2.3 V			0.4	.,
VOL	I _{OL} = 8 mA	3 V			0.44	V
	I _{OL} = 16 mA	4.5 V			0.55	
Ц	V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
loff	V_I or $V_O = 0$ to 5.5 V	0			5	μΑ
Ci	V _I = V _{CC} or GND	3.3 V		2.9		pF



SN74LV374A-EP OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C			MAX	
		MIN	MAX	MIN	WAX	UNIT
t _W	Pulse duration, CLK high or low	5		5.5		ns
t _{su}	Setup time, data before CLK↑	4.5		4.5		ns
th	Hold time, data after CLK↑	2		2	·	ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C	MINI	MAX	LINUT
		MIN	MAX	MIN	IVIAA	UNIT
t _W	Pulse duration, CLK high or low	5		5		ns
t _{su}	Setup time, data before CLK↑	3		3		ns
th	Hold time, data after CLK↑	2		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T _A = 25°C			BAINI	BA A V	LINUT
PARAMETER	(INPUT)	(INPUT) (OUTPUT)		MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				55	110		50		MHz
^t pd	CLK	Q			8.3	16.2	1	18.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		7.7	14.5	1	17.5	
^t dis	ŌĒ	Q			5.9	14	1	16	ns
tsk(o)						1.5			

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T _A = 25°C			BAINI	MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				85	170		75		MHz
t _{pd}	CLK	Q			5.9	10.1	1	13.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		5.5	9.6	1	13	
^t dis	ŌĒ	Q]		4	8.8	1	10	ns
tsk(o)						1			

SN74LV374A-EP **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS SCLS500A - MAY 2003 - REVISED MAY 2004

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

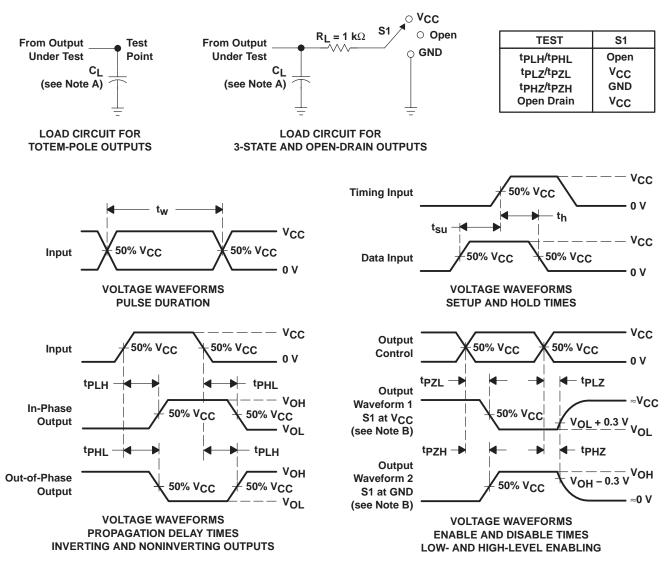
	PARAMETER				UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.6	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.5	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		2.9		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CO	VCC	TYP	UNIT	
<u> </u>	Down discinsting conscitones	Outpute enabled	C. F0 pF	f = 10 MHz	3.3 V	21.1	pF
Cpd	Power dissipation capacitance	Outputs enabled	$C_L = 50 pF$,	1 = 10 WITZ	5 V	22.8	pr

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpz and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV374ATPWREP	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03663-01XE	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV374A-EP:

Catalog: SN74LV374A

Automotive: SN74LV374A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV374ATPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV374ATPWREP	TSSOP	PW	20	2000	346.0	346.0	33.0

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